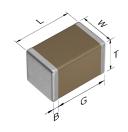
## 积层贴片陶瓷片式电容器

## C2012X5R0J226M085AB

RoHS Reach Halogen Free Pb Free

交货型号	C2012X5R0J226MT****
用途	一般等级
特点	General 一般(~75V)
系列	C2012 [EIA 0805]
状态	▲ 量产体制(新设计非推荐)



尺寸			
长度(L)	$2.00 \text{mm} \pm 0.20 \text{mm}$		
宽度(W)	1. 25mm ±0. 20mm		
厚度(T)	$0.85 \mathrm{mm}~\pm 0.15 \mathrm{mm}$		
端子宽度(B)	0.20mm Min.		
端子间隔(G)	0.50mm Min.		
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering)		
1世存/开盆41/月 (L n/	0.90mm to 1.20mm(Reflow Soldering)		
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)		
1世存/杆盆/11/问(LD)	0.70mm to 0.90mm(Reflow Soldering)		
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)		
1世行が土血(14)円(はし)	0.90mm to 1.20mm(Reflow Soldering)		

· · · · · · · · · · · · · · · · · · ·	气特性
电容	22 μ F ±20%
额定电压	6. 3VDC
温度特性	$X5R(\pm 15\%)$
耗散因数(Max.)	10%
绝缘电阻 (Min.)	4ΜΩ

	其他	
焊接方法	流体	
<b>坪</b> 接刀法	回流	
AEC-Q200	NO NO	
包装形式	纸编带 (180mm卷筒)	
包装个数	4000pcs	

<sup>!</sup> Images are for reference only and show exemplary products.

<sup>!</sup> This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

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特性图表(这是参考数据,并不保证产品的特性。)

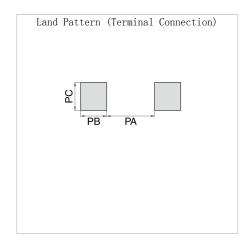
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## Associated Images



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